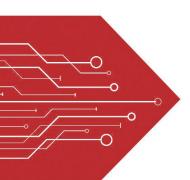
MSKSEMI















ESD

TVS

TSS

MOV

GDT

PLED

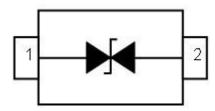
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SOD-523

FEATURES

♦ IEC61000-4-2 (ESD) ±8kV (Contact),

±15kV (Air)

IEC61000-4-4 (EFT) 40A (5/50ns)

♦ Peak power dissipation: 40W (8/20µs)

♦ Protects one I/O line

♦ Low clamping voltage

♦ Working voltages : 5V

♦ Low leakage current

♦ Low capacitance

MACHANICAL DATA

♦ SOD-523 package

♦ Terminals: Tin plated, solderable per MIL-STD-750, method 2026

♦ Packaging: Tape and Reel

♦ Reel size: 7 inch

♦ Weight: 0.0018 gram (approx.)

APPLICATIONS

- ♦ High Speed Line :USB1.0/2.0, VGA, DVI, SDI,
- ♦ Serial and Parallel Ports
- ♦ Notebooks, Desktops, Servers
- ♦ Projection TV
- ♦ Cellular handsets and accessories
- ♦ Portable instrumentation
- ♦ Peripherals







ABSOLUTE MAXIMUM RATING				
Symbol	Parameter	Value	Units	
V _{ESD}	ESD per IEC 61000-4-2 (Contact) ESD per IEC 61000-4-2 (Air)	±8 ±15	kV	
P _{PP}	Peak Pulse Power (8/20µs)	40	W	
T _{OPT}	Operating Temperature	-55~150	°C	
T _{STG}	Storage Temperature	-55~150	°C	

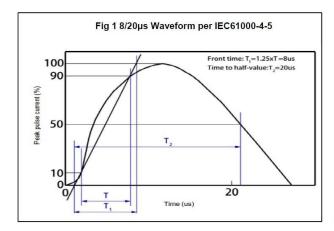
ELECTRICAL CHARACTERISTICS (Tamb=25°C)						
Symbol	Parameter	Test Condition	Min	Тур	Max	Units
V_{RWM}	Reverse Working Voltage				5.0	V
V_{BR}	Reverse Breakdown Voltage	I _T = 1mA	5.2		8.0	V
I _R	Reverse Leakage Current	V _{RWM} = 5V			2.0	μA
Vc	Clamping Voltage	$I_{PP} = 1A, t_p = 8/20 \mu s$			9	V
Сл	Junction Capacitance	V _R = 0V, f = 1MHz		4.5	6	pF

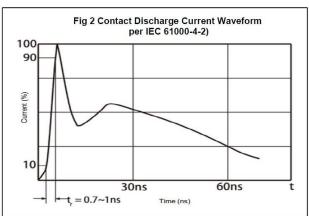


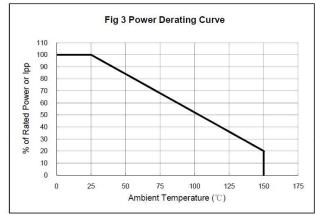


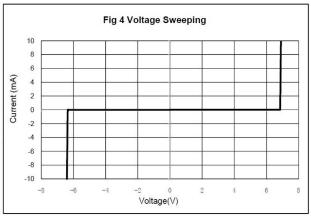


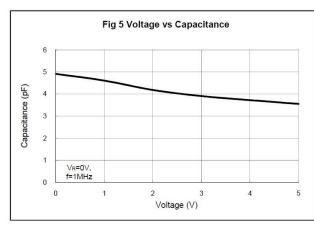


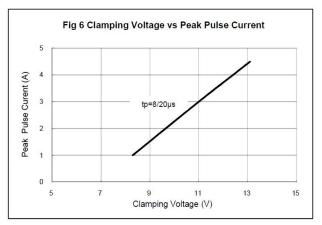








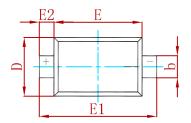


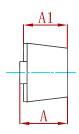


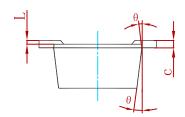




PACKAGE MECHANICAL DATA

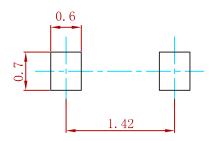






Symbol	Dimensions In Millimeters		Dimensions In Inches		
Syllibol	Min	Max	Min	Max	
Α	0.510	0.770	0.020	0.031	
A1	0.500	0.700	0.020	0.028	
b	0.250	0.350	0.010	0.014	
С	0.080	0.150	0.003	0.006	
D	0.750	0.850	0.030	0.033	
E	1.100	1.300	0.043	0.051	
E1	1.500	1.700	0.059	0.067	
E2	0.200	REF	0.008	REF	
L	0.010	0.070	0.001	0.003	
θ	7° I	REF	7° F	REF	

Suggested Pad Layout



Note:

- 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
- 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
ESD5B5CL-MS	SOD-523	3000



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